

NE8800K DISPENCING CONDITION

PANASERT HDPV HDPG3

	NOZZLE	dot diameter	Nozzle Heater (°C)	Dispecing Pressure (Mpa)	Dispencing Magnification	Stroke (mm)	Head up Speed	Head down Speed
1608Chip R&C	VS	Ø0.6mm±0.05	35	0.06	1.0	3	4	4
2125Chip R&C	S	Ø0.7mm±0.05		0.1	1.0	3		
3216Chip R&C	S	Ø0.8mm±0.05		0.1	1.2	3		
MELF	S(90°C)	Ø1.0mm±0.05		###	4			
タンタルC	L	Ø1.0mm±0.05		0.14	1.0	5		
タンタルD	L	Ø1.2mm±0.1		0.14	1.4	5		
SOIC	L	Ø1.4mm±0.1		0.14	2.1	5		

In case of dot standard quantity VS 23msec S 22msec L 22msec

PANASERT HDF

	NOZZLE	dot diameter	Nozzle Heater (°C)	Dispecing Pressure (Mpa)	Dispencing Magnification	Stroke (mm)	Head up Speed	Head down Speed
1608Chip R&C	VS	Ø0.6mm±0.05	35	0.06	1.0	3	1	1
2125Chip R&C	S	Ø0.7mm±0.05		0.1	1.0	3	1	1
3216Chip R&C	S	Ø0.8mm±0.05		0.1	1.5	4	1	1
MELF	S()	Ø1.0mm±0.05		3.8	7	1	1	
タンタルC	L	Ø1.0mm±0.05		0.14	1.9	6	1	1
タンタルD	L	Ø1.2mm±0.1		0.14	3.3	8	1	1
SOIC	L	Ø1.4mm±0.1		0.14	6.5	11	7	0

SANYO TDM 3000E/3500E

NOZZLE TYPE (ID)	Syringe up & down reducing (%)	Syringe Lebel	Nozzle Heater (°C)	X/Y moving slow down	Dispecing Pressure (Mpa)	Dispencing Tact Max speed
100*	0	L lebel	35	NO	0.1	0.08sec
200*	20	L lebel				0.10sec
201*	50	L lebel				0.14sec
300*	80	H lebel				0.40sec